APPLICA	BLE STAN	DARD								
VOLTAGE			150 V AC CUI					1 A		
RATING	OPERATING TEMPERATURE RANGE		-35°C TO +85 °C(NOTES 1)		STORAGE TEMPERAT			-10°C TO +60°C (NOTI)
	OPERATING HUMIDITY RAI	NGE	20 % TO 80 % (NOTES 2) S		STORAGE HUMIDITY			20 % TO 70 %(NO	<u> </u>	
	APPLICABLE CONNECTOR		1 0110-00-1.200 1		APPLICABL CONTACT	PELICABLE DF13 (G) -2630SC DF13-3032SCFA				
			SPEC	CIFICA	TIONS			DI 10 0002001	•	
IT	EM		TEST METHOD			R	EQUIRE	EMENTS	QT	A-
CONSTR	RUCTION									
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACCC	ACCORDING TO DRAWING.				Х
MARKING			ED VISUALLY.						Х	<u> </u>
	IC CHARA				laa -				Х	
		100 m A (DC OR 1000 Hz).				30 mΩ MAX.				┝
INSULATION RESISTANCE		100 V DC.			500 M	Ω MIN.			Х	-
VOLTAGE PROOF		500 V AC FOR 1 min.			NO FL	ASHOVE	R OR BI	REAKDOWN.	Х	†-
MECHAN	NICAL CHA	RACTE	RISTICS							
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.			② NO	 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			Х	-
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.				① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF			Х	_
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			ES PA	PARTS.			Х	-
		CHARA	ACTERISTICS							
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow +85 \rightarrow 5 TO 35 $^{\circ}$ C TIME 30 \rightarrow 10 TO 15 \rightarrow 30 \rightarrow 10 TO 15 min UNDER 5 CYCLES.			min 2 INS	 ① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				-
DAMP HEAT		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			OF					
(STEADY STATE) RESISTANCE TO		1) REFLOW SOLDERING			NO DE					╁╴
SOLDERING HEAT		≪REFLOW AREA≫ MAX250°C WITHIN 10 sec MIN 230°C WITHIN 60 sec ≪PREHEATING AREA≫ 170°C to 190°C 60 to 120 sec PUT THROUGH IN REFLOW FURNACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT.				EXCESSIVE LOOSENESS OF THE TERMINALS.				
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE,			I .	SOLDER SHALL COVER A MINIMUM OF				
NOTE2:NO CO NOTE3:APPL` AFTEF	ONDENSING Y TO THE CONE R PCB BOARD ,	ERATURE F DITION OF L OPERATIN	PR INSERTION DURATION, RISING BY CURRENT ONG TERM STORAGE FOR G TEMPERATURE AND HUM ON OF REVISIONS	UNUSED PR	ODUCTS BEF	OR PCB ON	N BOARD			ON.
COLIN	-							5.1201120		
COUN			to JIS C 5402.			APPROVED		HK. UMEHARA		0.0
Δ	I erwise specif	ied, refer	10 010 0 0402.				ED			0.0
Δ	I erwise specif	ied, refer	10 010 0 0402.			CHECK	·	HK. UMEHARA	11.1	0. 0
<u> </u>	I erwise specif	ied, refer	10 010 0 0402.			DESIGN		HK. UMEHARA HT. SATO	11. 1 11. 1	
<u> </u>	l erwise specif	ied, refer		Ţ			IED			0.0
Jnless othe	·		urance Test X:Applicable To	est	DRAWII	DESIGN DRAW	IED	HT. SATO	11. 1 11. 0	0.0
Jnless othe	ualification Tes	t AT:Ass			DRAWII PART NO.	DESIGN DRAW	IED /N	HT.SATO MI.SAKIMURA	11. 1 11. 0	0.0